

# Lenovo PX

Version: 5.0 | 03/19/2024

## Product Display Name

---

Information Date	22-Aug-23
Hardware Maintenance Manual	<a href="#">HMM</a>
Drivers & Software	<a href="#">Drivers &amp; Software</a>
Available Whitepapers	<a href="#">Power Configurator</a> <a href="#">Memory Configurator</a> <a href="#">Storage Configurator</a> <a href="#">Intel VROC Configurator</a> <a href="#">Discrete RAID Configurator</a> <a href="#">Windows 11 Installation</a> <a href="#">Windows 10 Installation</a> <a href="#">Red Hat Enterprise Linux 9 Installation</a> <a href="#">Ubuntu Linux 22.04 LTS Installation</a>
Description	The pinnacle of Lenovo technology, the ThinkStationPX goes beyond the limits of desktop performance to enable even the most extreme workflows. Featuring a thermally advanced chassis co-designed with Aston Martin, the latest dual 4th Gen Intel® Xeon® Scalable processors, up to 120 cores, and support for up to four NVIDIA RTX™6000 Ada Generation GPUs, this workstation powerhouse runs the most complex computing workloads seamlessly.

## CPU

---

Processor Support	Dual 4th Generation Intel Xeon Scalable Processors
Socket Type	Socket-E (LGA-4677)
Disclaimers	

## Operating Systems

---

Preloaded	Windows 11 Pro 64-bit for Workstation Ubuntu 22.04 LTS (configuration specific)
Supported	Red Hat Enterprise Linux 9.x

	Ubuntu 22.04 LTS
Disclaimers	

## Memory

---

Slots	Up to 16 DIMMS (8 DIMMs per CPU)
Channels	8 Memory Channels per CPU
Type	DDR5, 288-Pin, ECC RDIMM and 3DS RDIMM*
ECC Support	Yes
Speed	Up to 4800MHz
Max DIMM Size	64GB DDR5 ECC RDIMM 128GB DDR5 ECC 3DS-RDIMM
Max System Memory	2TB
Disclaimers	*Actual Memory Speed is dependent on the CPU.

## Storage

---

Total Bays/Size	Up to 4
SATA	3 x SFF-8680 Receptacles 1 x SATA 3.0 Connectors
PCIe (M.2)	3 x M.2 NVMe 2280 PCIe Connectors Onboard 4 x M.2 NVMe 2280 Front Accessible Drives
Disclaimers	*See Storage Whitepaper for details on the available usage options.

## Video

---

Integrated Graphics	Not Available
Discrete Graphics	NVIDIA T400(MiniDP x3) – 4GB GDDR6, PCIe3, Single-Slot NVIDIA T1000(MiniDP x4) – 8GB GDDR6, PCIe3, Single-Slot NVIDIA RTX A2000(MiniDP x4) – 12GB GDDR6, PCIe4, Dual-Slot NVIDIA RTX A4000 (4xDP) – 16GB GDDR6, PCIe4, Single-Slot NVIDIA RTX A4500(DP x4) – 20GB, GDDR6, PCIe4, Dual-Slot NVIDIA RTX A5500(DP x4) – 24GB GDDR6, PCIe4, Dual-Slot NVIDIA RTX A6000(DP x4) – 48GB GDDR6, PCIe4, Dual-Slot NVIDIA RTX6000 Ada(DP x4) – 48GB GDDR6, PCIe4, Dual-Slot NVIDIA Quadro SYNC II card
Multi-GPU Support	Yes
Type	PCIe Add-In-Card

Bus Interface	PCIe x16
Disclaimers	

## Slots

---

Slot 1	PCIe 4.0 x16, Full Height, Full Length, 75W (CPU 2)
Slot 2	PCIe 4.0 x16, Full Height, Full Length, 75W (CPU 2)
Slot 3	PCIe 5.0 x16, Full Height, Full Length, 75W (CPU 2)
Slot 4	PCIe 5.0 x16, Full Height, Full Length, 75W (CPU 2)
Slot 5	PCIe 4.0 x8, Full Height, Full Length, 25W, Open Ended (CPU 2)
Slot 6	PCIe 5.0 x16, Full Height, Full Length, 75W (CPU 1)
Slot 7	PCIe 4.0 x16, Full Height, Full Length, 75W (CPU 1)
Slot 8	PCIe 5.0 x16, Full Height, Full Length, 75W (CPU 1)
Slot 9	PCIe 4.0 x16, Full Height, Full Length, 75W (CPU 1)
Disclaimers	

## Front I/O

---

USB	1 x USB-A 3.2 Gen 2 (10Gbps) 1 x USB-A 3.2 Gen 2 (10Gbps) (with Always On Charging) 2 x USB-C 3.2 Gen 2 (10Gbps)
Audio	1 x 3.5mm Global Headset Jack (Headphone + Mic in)
Media Card Reader	N/A
Flex Bay	3 x Front access drive bay Rear Flex Storage Enclosure (Shared with 2nd PSU Bay)
Disclaimers	Note: Actual USB throughput will vary depending on the type and quantity of USB devices used.

## Rear I/O

---

USB	2 x USB-A 2.0 (480Mbps) 4 x USB-A 3.2 Gen 1 (5Gbps) 1 x USB-C 3.2 Gen 2x2 (20Gbps)
Audio	2 x Rear (Line Out, Line In retasked as Mic)
DisplayPort	As Supported by GPU
HDMI	As Supported by GPU

Serial Port	Optional 1x Rear Port
Ethernet	1 x 1GbE – RJ45 1 x 10GbE – RJ45
PS/2	Optional PS/2 (2 port) PCIe adapter
Optional Network Adapter	Broadcom 5720 Dual Port Gigabit PCIe Ethernet Adapter Broadcom 5719 Quad Port Gigabit PCIe Ethernet Adapter Bitland RTL8168H 1000M PCIe Ethernet Adapter Intel I210-T1 Single Port Gigabit PCIe Ethernet Adapter Intel I350-T2 Dual Port Gigabit PCIe Ethernet Adapter Intel I350-T4 Quad Port Gigabit PCIe Ethernet Adapter Intel AX210 WIFI PCIe Adapter with Internal Antennas
Disclaimers	Note: Actual USB throughput will vary depending on the type and quantity of USB devices used.

## Ethernet

---

Vendor	Aquantia 10 GbE AQC113C-B1-C Intel 1 GbE I219 (Vpro, AMT)
Speeds	10/100/1000/10000Mbps Aquantia AQC113C 10/100/1000Mbps Intel I219
Functions	PXE, WOL, Jumbo Frames ASF, Teaming (Intel only)
Connectors	2 x RJ45
Disclaimers	Note: Network speeds listed are theoretical.

## Audio

---

Vendor	Realtek
Type	HD (2.0)
Internal Speaker	1 x 1.5 watt 4 ohm
Connectors	2 x Rear 3.5mm Jacks (Line Out, Line In retasked as Mic) 1 x Front 3.5mm Global Headset Jack (Headphone + Mic in)
Chipset	Realtek ALC897Q Codec (rear) Realtec ALC4032 (front)
Number of Channels	Rear Audio: 2 Channels Front Audio: 2 Channels
Number of Bits/Audio Resolution	Rear Codec: 10 Channel DAC Supports 16/20/24-bit PCM 2 Stereo ADC Supports 16/20/24-bit PCM Front Codec: One stereo DAC supports 8/16/22.05/24/32/44.1/48/96/176.4/192KHz Sample Rate, 16/24-bit One stereo ADC supports 8/16/22.05/24/32/44.1/48/96KHz Sample Rate, 16/24-bit
Disclaimers	*Note: Audio Codec ALC897Q can support 7.1 channel, but motherboard

only has 2 rear jacks – MIC in and Line out, only 2 channel for Line out.

## Thermal

---

Temp Sensors	Ambient Cabled Sensor – Thermistor, MB Header cabled to chassis front bezel PCIe Zone 1 Sensor – Thermistor PCIe Zone 2 Sensor – Thermistor PCIe Zone 3 Sensor – Thermistor PCIe Zone 4 Sensor – Thermistor M.2 Zone 1 Sensor – Thermistor M.2 Zone 2 Sensor – Thermistor MISC Sensor – Thermistor HDD 1 Sensor – I2C Temp Sensor HDD 2 Sensor – I2C Temp Sensor HDD 3 Sensor – I2C Temp Sensor PSU Bay 2 (HDD) Sensor – I2C Temp Sensor
Fans	2 x Front Fans (FRONT_FAN1) – 6-pin blind connect 1 Connector per 2 Fans 1 x Front Fan (FRONT_FAN2) – 4-pin blind connect 1 Connector per 1 Fans 1 x Front Fan (FRONT_FAN3) – 4-pin blind connect 1 Connector per 1 Fans 2 x Rear Fans (REAR_FAN1) – 6-pin blind connect 1 Connector per 2 Fans 1 x CPU 1 Fan (CPU1_FAN) – 4-pin header with 3-pin key 1 x CPU 2 Fan (CPU2_FAN) – 4-pin header with 3-pin key 1 x PSU HDD Fan (PSU_HDD_FAN) – PSU Edge Connector 3 x HDD Fans (HDD_FAN_X) – 4-pin header with 3-pin key 2 x PSU1 Fans – internal of PSU 2 x PSU2 Fans – internal of PSU 1 x CPU1 Memory Fan – CPU1_Pump_DDR – 4-pin header with 3-pin key 1 x CPU2 Memory Fan – CPU2_Pump_DDR – 4-pin header with 3-pin key
Disclaimers	

## Power Specifications

---

Power Supply	1850 watts
Power Efficiency	92% Efficient @ 50% Load
Main	C20
Operating Voltage Range	100 – 240V (autosensing)
Rated Voltage Range	90-264VAC
Rated Line Frequency	47Hz / 63Hz
Operating Line Frequency Range	50Hz / 60Hz
Rated Input Current	13 – 20A
Graphics	Up to 8 x 8-pin (6+2) PCIe*
Power Supply Fan	Yes

ENERGY STAR® Qualified (config dependent)	Yes
80 PLUS Compliant	Yes
Built-in Self Test (BIST) LED	Yes
Disclaimers	*Quantity of Graphics power cables is configuration dependent *See Power Configuration Whitepaper for additional details.

## BIOS

---

Vendor	AMI
Disclaimers	

## Chassis Information

---

Color	Storm Gray
PSU	One Fixed 1850W, Autosensing, 92% PSU, 80 PLUS Platinum Qualified Optional: 2nd 1850W, Autosensing, 92% PSU, 80 PLUS Platinum Qualified
Thermal Solutions	2 Rear Fans 4 Front Fans 1 Fan per storage bay 1 Fan per CPU 2 Fans per PSU Memory Fans (configuration dependent)
Dimensions	434.4mm/17.1" H (without feet) 440.4mm/17.3" H (with feet) 575mm/22.6" D 220mm/8.7" W
Weight	35.6 kg / 78.48 lbs
Disclaimers	

## Packaging Dimensions

---

Height (mm/in)	658mm / 25.91"
Width (mm/in)	397mm / 15.63"
Depth (mm/in)	802mm / 31.57"
Weight (kgs/lbs)	40.135 kg / 88.48 lbs
Disclaimers	

## Security & Serviceability

---

TPM	Infineon SPI TPM SLB9672 TPM 2.0
Asset ID	Yes, 1024 x 8bit
vPro	Yes
Cable Lock Support	Yes, Optional Kensington Cable Lock
Serial, Parallel, USB, Audio, Network, Enable/Disable Port Control	Yes
Power-On Password	Yes
Setup Password	Yes
NIC LEDs (integrated)	Yes
Access Panel Key Lock	Yes
Boot Sequence Control	Yes
Padlock Support	No
Boot Without Keyboard and/or Mouse	Yes
Access Panel	Tool-less Side Cover Removal
Hard Drives	Tool-less
Expansion Cards	Tool-less
Processor Socket	Tool-less*
Color Coded User Touch Points	Yes
Color-coordinated Cables and Connectors	Yes
Memory	Tool-less
System Board	Retained with Screws
Restore CD/DVD/USB Set	Not Included, Restore Media Available via Lenovo Download Recovery Service or available through Lenovo Support.
Disclaimers	*Note: CPU Heatsink assembly requires a T30 bit.

## Operating Environment

---

Air Temperature	Operating: 10°C to 35°C (50°F to 95°F)
Storage	Storage: -40°C to 60°C (-40°F to 140°F) in Original Shipping Carton Storage: -10°C to 60°C (14°F to 140°F) Without Carton
Humidity	Relative Humidity Operating: 10% to 80% (non-condensing) Relative Humidity Storage/Transit: 10% to 90% (non-condensing) Wet Bulb Temperature Operating: 25°C (77°F) max Wet Bulb Temperature Non-operating: 40°C (104°F) max

Altitude	Upper limits decrease 1°C (1.8°F) per 300 m (1000 ft) above sea level
Vibration	Operating Vibration: Random,0.27G at 5-500 Hz, 30 Minutes Per Surface (X,Y,Z) Non-Operating Vibration: Random,1.04G at 2-200 Hz, 15 Minutes Per Surface (±X,±Y,±Z)
Shock	Operating: X,Y axis: +- 15G/3ms Z axis: +- 30G/3ms Operating (Rack mounted): X,Y,Z axis: +- 15G/3ms Non-operating target: Trapezoidal shock, 35g average, 11ms
Disclaimers	Extended operating temperatures are possible – please contact your Lenovo Rep
Board Size	16.26" x 15.43" (413mm x 392mm)
Layout	Lenovo Custom Extended ATX

## Motherboard Core

---

Processor Support	Intel Sapphire Rapids – Xeon Scalable Processors (Platinum, Gold, Silver)
Socket Type	Socket E (LGA 4677)
Memory Support	DDR5 up to 4800MHz RDIMM / 3DS RDIMM Memory
CPU-CPU Interconnect	Intel UPI v2.0, 3 links, x24, at speeds 12.8GT/s, 14.4GT/S and 16GT/s
Voltage Regulator	Intel VR14.0 – 400W TDP Capable
Chipset (PCH)	Intel Emmitsburg (Intel C741 Series)
Flash	2 x 64MB
Super I/O	2 x MEC1723(176 pin)
Clock	External Clock
Audio	Rear Codec: Realtek ALC897Q (Rear I/O) Front Codec: Realtek ALC4032 (FPIO)
Ethernet	Aquantia 10Gb AQC113C-B1-C Intel 1Gb I219

## Supported Components

---

Processor Level	Intel Xeon Platinum	Intel Xeon Gold	Intel Xeon Silver
Processor	Intel XEON Sapphire Rapids Platinum 8490H Intel XEON Sapphire Rapids Platinum 8468	Intel XEON Sapphire Rapids Gold 6442Y Intel XEON Sapphire Rapids Gold 6438Y+ Intel XEON Sapphire Rapids Gold 6430 Intel XEON Sapphire Rapids Gold 6418H Intel XEON Sapphire Rapids Gold 6416H Intel XEON Sapphire Rapids Gold 5420+ Intel XEON Sapphire	Intel XEON Sapphire Rapids Silver 4416+ Intel XEON Sapphire Rapids Silver 4410Y Intel XEON Sapphire Rapids Silver 4410T



		Rapids Gold 5418Y Intel XEON Sapphire Rapids Gold 5416S Intel XEON Sapphire Rapids Gold 5415+
Memory Type	RDIMMs – 4800MHz, CPU Dependent	3DS-RDIMMs – 4800MHz, CPU Dependent
Memory	16GB DDR5 ECC RDIMM PC5-4800 32GB DDR5 ECC RDIMM PC5- 4800 64GB DDR5 ECC RDIMM PC5- 4800	128GB DDR5 ECC 3DS-RDIMM PC5-4800
Disclaimers	Additional CPU SKU's certified.	

## Storage

---

3.5" SATA Hard Disk Drive (HDD)	2TB SATA – 7200rpm, 6Gb/s, 3.5" 6TB SATA – 7200rpm, 6Gb/s, 3.5" (Enterprise Class) 12TB SATA – 7200rpm, 6Gb/s, 3.5" (Enterprise Class)
M.2 PCIe Solid State Drive (SSD)	512GB M.2 PCIe – SSD, 2280, Gen4 (x4), NVMe, TLC, OPAL2.0 1024GB M.2 PCIe – SSD, 2280, Gen4 (x4), NVMe, TLC, OPAL2.0 2048GB M.2 PCIe – SSD, 2280, Gen4 (x4), NVMe, TLC, OPAL2.0 4096GB M.2 PCIe – SSD, 2280, Gen4 (x4), NVMe, TLC, OPAL2.0
Disclaimers	Additional Storage devices certified.

## RAID

---

RAID Requirements	M.2 and SATA RAID via Intel VROC Controller
Notes	Supported RAID levels for a system will vary from the stated capabilities of the RAID controller due to dependencies on the number and capacity of physical disks in the system and on customer requirements for performance, fault tolerance, or data redundancy. Max supported RAID 0/1/5/10.
Intel VROC	Intel Virtual RAID On CPU (VROC) – Basic, Supports 0/1/10 Intel Virtual RAID On CPU (VROC) – Premium, Supports 0/1/5/10

## Keyboard And Pointing Devices

---

Keyboard	USB Traditional Keyboard PS/2 Tradition Keyboard Smart Card Keyboard USB Calliope Keyboard
Pointing Devices	USB Fingerprint Mouse USB Calliope Mouse



## HDD Specifications

---

Drive	500GB SATA – 7200rpm, 6Gb/s, 2.5"	1TB SATA – 7200rpm, 6Gb/s, 3.5"	2TB SATA – 7200rpm, 6Gb/s, 3.5"	4TB SATA – 7200rpm, 6Gb/s, 3.5"	6TB SATA – 7200rpm, 6Gb/s, 3.5"
3.5" SATA Hard Disk Drive (HDD)	Not Available	Yes	Yes	Yes	Yes
2.5" SATA Hard Disk Drive (HDD)	Yes	Not Available	Not Available	Not Available	Not Available
Connector	SATA	SATA	SATA	SATA	SATA
Transfer Rate (Gb/sec)	160MB/s OD read	Average data rate, read/write 156MB/s	Average data rate, read/write 156MB/s	Sustained data transfer rate 216 – 226MB/s	Sustained data transfer rate 216 – 226MB/s
Spindle Speed (RPM)	7,200	7,200	7,200	7,200	7,200
DC Power to Drive Ready (sec)	3.5	<10.0	<17.0	<17.0	<17.0
Average Latency (msec)	4.2	4.16	4.16	4.16	4.16
Input (VDC)	5	5	5	5	5
Typical (Watts)	1.9	6.19	6.7	7.35	8.13
Idle (Watts)	0.7	4.6	4.5	5.45	6.21
Physical Dimensions	69.85mm x 100.34mm x 7mm	101.6mm x 146.99mm x 19.88mm	101.6mm x 146.99mm x 26.1mm	101.85mm x 147mm x 26.1mm	101.85mm x 147mm x 26.1mm
Weight (grams)	90	420	535	680	705
Operating (C) Ambient	0 to 60	0 to 60	0 to 60	5 to 60	5 to 60
Operating (C) Base Casting	60	60	60	60	60
Non-Operating (C) Ambient	(-40 to 70)	(-40 to 70)	(-40 to 70)	(-40 to 70)	(-40 to 70)
Gradient (C per Hour)	20	20	20	20	20
Operating (Gs @ 2ms)	400	70	80	Read 70 Gs / Write 40 Gs	Read 70 Gs / Write 40 Gs
Non-Operating (Gs @ 2ms)	1000	350	300	300	250
Disclaimers					

## Solid State Storage Specifications

---

Drive	256GB 2.5" SATA SSD	512GB 2.5" SATA SSD	1TB 2.5" SATA SSD	2TB 2.5" SATA SSD	256GB NVMe M.2 SSD TLC	512GB NVMe M.2 SSD TLC	1024GB NVMe M.2 SSD TLC	2048GB NVMe M.2 SSD TLC	480GB AIC Optane™ SSD	1.5TB U.2 Optane™ SSD
Dimensions Millimeters (W x D x H)	70 x 100 x 7.0	70 x 100 x 7.0	70 x 100 x 7.0	70 x 100 x 7.0	22 x 80 x 2.3	22 x 80 x 2.3	22 x 80 x 2.3	22 x 80 x 2.3	20 x 168 x 104	70 x 100 x 15

Interface Type	SATA -III	SATA -III	SATA -III	SATA -III	PCIe Gen 3.0 x4 NVM e	PCIe Gen 3.0 x4 NVM e	PCIe Gen 3.0 x4 NVM e	PCIe Gen 3.0 x4 NVM e	PCIe Gen 3.0 x4 NVM e	PCIe Gen 3.0 x4 NVM e
Power Active (AVG)	1.8W	1.9W	2.2W	6W	5W	5W	5W	5W	18W	18W
Power Idle	50mW	50mW	50mW	50mW	50mW	50mW	50mW	50mW	7W	7W
Typical Sequential Read	540 MB/s	540 MB/s	540 MB/s	530 MB/s	3000 MB/s	3200 MB/s	3200 MB/s	3500 MB/s	2700 MB/s	2700 MB/s
Typical Sequential Write	500 MB/s	500 MB/s	500 MB/s	500 MB/s	1300 MB/s	1600 MB/s	1600 MB/s	3000 MB/s	2200 MB/s	2200 MB/s
Operating Temperature Range	0 to 55°C	0 to 55°C	0 to 55°C	0 to 55°C	0 to 55°C	0 to 55°C	0 to 55°C	0 to 55°C	0 to 85°C	0 to 85°C
Endurance Rating (Lifetime Writes)	85TB	150TB	300TB	600TB	85TB	150TB	300TB	600TB	8.76PB	27.3PB
Mean Time Between Failures (MTBF)	2.0M POH	2.0M POH	2.0M POH	2.0M POH	2.0M POH	2.0M POH	2.0M POH	2.0M POH	2.0M POH	2.0M POH
Hardware Encryption	AES 256 bit	AES 256 bit	AES 256 bit	AES 256 bit	AES 256 bit	AES 256 bit	AES 256 bit	AES 256 bit	No	No
Disclaimers	SSD performance measured with Crystal Disk Mark version 6.0.2 with the default 1000 MB data set. Sequential measurements are with 1 Thread, Queue-Depth 32. Random measurements are with 4 threads and queue-depth 32.									

## HDD Controllers

---

PCI Bus	PCH Integrated
PCI Modes	SATA 3.0
RAID Levels	0/1/5/10
Data Transfer Rates	6Gb/s
Internal Connectors	2 x MiniSAS HD (2 ports each) + 3 x SATA
Disclaimers	

## Optical Drive Specifications

---

Operating Systems Supported	Windows 10 Pro for Workstations (Preload) Windows 7 Pro 64 Red Hat Enterprise Linux 7.3 Ubuntu 16.04 and 18.04.2
Temperature	10° – 35°C (50° – 95°F)
Relative Humidity	10%-80% (non-condensing)

Maximum Wet Bulb Temperature	25°C max
Disclaimers	

## Integrated Graphics Adapter

---

Disclaimers	
-------------	--

## Discrete Graphics Adapter

---

Adapter	T400	T1000	RTX A2000	RTX A4000	RTX A4500	RTX A5500	RTX A6000	RTX 6000 Ada
Bus Interface	PCIe 3.0 x16	PCIe 3.0 x16	PCIe 4.0 x16	PCIe 4.0 x16	PCIe 4.0 x16	PCIe 4.0 x16	PCIe 4.0 x16	Coming Soon
Display Interface	3 x mDP 1.4	4 x mDP 1.4	4 x mDP 1.4a	4 x DP 1.4a	4 x DP 1.4	4 x DP 1.4a	4 x DP 1.4a	Coming Soon
Graphics Chipset	Turing	Turing	Coming Soon	Amper e	Coming Soon	Coming Soon	Amper e	Coming Soon
Memory Clock Frequency (MHz)	Coming Soon	Coming Soon	Coming Soon	Coming Soon	Coming Soon	Coming Soon	2000M Hz	Coming Soon
Memory Size	2GB GDDR 6	4GB GDDR 6	Coming Soon	16GB GDDR 6	Coming Soon	Coming Soon	48GB GDDR 6	Coming Soon
Memory Interface	64-bit	128-bit	Coming Soon	256-bit	Coming Soon	Coming Soon	384-bit	Coming Soon
Memory Bandwidth	80GB/s	160GB/s	Coming Soon	448 GB/s	Coming Soon	Coming Soon	Up to 768GB/s	Coming Soon
GPU Cores	CUDA Cores: 384	CUDA Cores: 896	Coming Soon	CUDA Cores: 6411 Tensor Cores: 192 RT Cores: 48	Coming Soon	Coming Soon	CUDA Cores: 10,752 Tensor Cores: 336 RT Cores: 84	Coming Soon
Maximum Power Consumption	30W	50W	Coming Soon	140W	Coming Soon	Coming Soon	300W	Coming Soon
Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or Digital)	Coming Soon	4 x 4096×2160 @ 120Hz 4 x 5120×2880 @ 60Hz 2 x	Coming Soon	Coming Soon	Coming Soon	4 x 4096×2160 @ 120Hz 4 x 5120×2880 @ 60Hz 2 x	Coming Soon	Coming Soon

	7680×4320 @ 60Hz			7680×4320 @ 60Hz				
Thermal Solution	Active	Active	Coming Soon	Active	Coming Soon	Coming Soon	Active	Coming Soon
Dimension	2.7" H x 6.1" L Single Slot	2.7" H x 6.1" L Single Slot	Coming Soon	4.4" H x 9.5" L Single Slot	Coming Soon	Coming Soon	4.4" H x 10.5" L Dual Slot, Full Height	Coming Soon
Advanced Display	Coming Soon	Coming Soon	Coming Soon	SYNC 2	Coming Soon	Coming Soon	SYNC 2	Coming Soon
SLI/NVLink Support	Coming Soon	Coming Soon	Coming Soon	Coming Soon	Coming Soon	Coming Soon	NVLink	Coming Soon
Disclaimers								

## Ethernet Specifications

Card	Intel I210-T1 Single Port Gigabit Ethernet Adapter (Springville)	Intel I350-T2 Dual Port Gigabit Ethernet Adapter (Stony Lake T2)	Intel I350-T4 Quad Port Gigabit Ethernet Adapter (Stony Lake T4)	Intel X540-T2 Dual Port Copper 10Gb Ethernet Adapter	Intel X710-DA2 Dual Port Fiber 10Gb Ethernet Adapter	Intel Ethernet SFP+ SR Optics Module	Intel Dual Band Wireless-AC 7260 ASM	Intel Winstorm Peak 8265 2x2 AC+BT 4.2 Vpro M.2 Combo
Supplier PN	I210T1, MM# 941033	I350T2 G1P20, MM# 928941	I350T4 G1P20, MM# 928942	MM#9 28955	MM# 952103	MM#: 941243	7260H MWDT X.R, MM# 936170	MM#: 946658
Data Rates Supported	10/100/1000Mbps copper	10/100/1000Mbps (Copper), 1000Mbps (Fiber)	10/100/1000Mbps (Copper), 1000Mbps (Fiber)	100/1000Mbps and 10Gbps Copper	1GbE/10GbE Optical fiber 10GbE Direct Attach (DAC)	Not Available	Intel Dual Band Wireless-AC 7260	Intel Dual Band Wireless-AC 8265
Controller Details	Intel® Ethernet Controller I210	Intel Ethernet Controller I350	Intel Ethernet Controller I351	Intel Ethernet Controller X540	Intel Ethernet Controller X710-AM2	Not Available	Intel Dual Band Wireless-AC 7260, Dual Band, 2x2, WiFi+BT	Intel Dual Band Wireless-AC 8265, 2x2, WiFi+BT, MU-MIMO
Controller Bus Architecture	PCIe 2.1 (5GT/s)	PCIe 2.1 (5GT/s)	PCIe 2.1 (5GT/s)	PCIe 2.1 (5GT/s)	PCIe 3.0 (8GT/s)	Not Available	PCIe M.2	PCIe M.2

Data Transfer Mode	Ethernet	Ethernet	Ethernet	Ethernet	Ethernet	Not Available	WiFi (802.11ac), 2.4GHz, 5GHz	WiFi (802.11ac), 2.4GHz, 5GHz
Power Consumption	0.81W	Copper: I350-T2 V2= 4.4W Fiber: I350-F2= 5.5W	Copper: I350T4 V2= 5W LC-Fiber: I350F4= 6W	X540-T2: 10Gps= 17.4W 1Gbps= 9.5W 100Mbps= 6.6W X540-T1: 10Gbps= 10.8W 1Gbps= 7.7W 100Mbps= 6.4W	Dual-port 10GBASE-SR= 4.3W typ/4.8W max Dual-port 1000BASE-SX= 4W typ/4.3W max Dual-port 10GBASE-LR= 4.5W typ/5.1W max Dual-port Direct Attach (Twinx)= 3.3W typ/3.7W max	Not Available	Not Available	Not Available
IEEE Standards Compliance	IEEE 802.3/10BASE-T, 100BASE-TX, 1000BASE-T	IEEE 802.3/10BASE-T, 100BASE-TX, 1000BASE-T	IEEE 802.3/10BASE-T, 100BASE-TX, 1000BASE-T	IEEE 802.3 100/1000/10G BASE-T	IEEE 802.3 1/10/100BASE-SR/LR, SFF-8431 10GSFP+DAC	Not Available	IEEE 802.11a bgn, 802.11ac, 802.11d, 802.11e, 802.11i, 802.11h, 802.11w	IEEE 802.11a bgn, 802.11ac, 802.11d, 802.11e, 802.11i, 802.11h, 802.11w, 802.11r, 802.11k, 802.11v (pending)
Boot ROM Support	PXE boot, Intel iSCSI Remote Boot for Windows, Linux and Vmware, Intel BootAgent Software via PXE or BootP,	PXE boot, Intel iSCSI Remote Boot for Windows, Linux and Vmware, Intel BootAgent Software via PXE or BootP,	PXE boot, Intel iSCSI Remote Boot for Windows, Linux and Vmware, Intel BootAgent Software via PXE or BootP,	PXE boot, Intel iSCSI Remote Boot for Windows, Linux and Vmware, Intel BootAgent Software via PXE or BootP,	PXE boot, Intel iSCSI Remote Boot for Windows, Linux and Vmware, Intel BootAgent Software via PXE or BootP,	Not Available	Not Available	Not Available

	WDMS or UEFI	WDMS or UEFI	WDMS or UEFI	WDMS or UEFI	WDMS or UEFI			
Network Transfer Mode (Full/Half Duplex)	Supported	Supported	Supported	Supported	Supported	Not Available	Not Available	Not Available
Network Transfer Rate	1,000M bps Full Duplex	1,000M bps Full Duplex	1,000M bps Full Duplex	1,000M bps Full Duplex	1,000M bps Full Duplex	Not Available	300/867Mbps	867Mbps
Operating System Driver Support	Windows 7/8/10, Linux, FreeBSD, XEN, VMware	Windows 7/8/10, Linux, FreeBSD, XEN, VMware	Windows 7/8/10, Linux, FreeBSD, XEN, VMware	Windows 7/8/10, Windows Server Linux, FreeBSD	Windows 2008, 2012; RHEL 6.5/7.0, FreeBSD 9/10, VMware ESXi 5.x	Not Available	Windows 10, 32-bit*, Windows 10, 64-bit*, Windows 8.1, 32-bit*, Windows 8.1, 64-bit*, Windows 8, 32-bit*, Windows 8, 64-bit*, Windows 7, 32-bit*, Windows 7, 64-bit*, Linux*	Windows 10, 64-bit*, Windows 8.1, 64-bit*, Windows 7, 32-bit*, Windows 7, 64-bit*, Linux*
Manageability	Supported	Supported	Supported	Supported	Supported	Not Available	Not Available	Not Available
Manageability Capabilities Alerting	Supported	Supported	Supported	Supported	Supported	Not Available	Not Available	Not Available
TDP	Firmware Based Thermal Management	Firmware Based Thermal Management	Firmware Based Thermal Management	Firmware Based Thermal Management	Not Available	Not Available	Not Available	Not Available
Operating Temperature Range	0°C to 55°C (32°F to 131°F)	0°C to 55°C (32°F to 131°F)	0°C to 55°C (32°F to 131°F)	0°C to 55°C (32°F to 131°F)	0°C to 55°C (32°F to 131°F)	Not Available	0°C to 80°C (32°F to 176°F)	0°C to 80°C (32°F to 176°F)
# of Ports	1	2	4	2	2	Not Available	Not Available	Not Available
Data Rate Per Port	10/100/1000M bps (copper)	10/100/1000M bps (copper), 1000M bps (fiber)	10/100/1000M bps (copper), 1000M bps (fiber)	100/1,000Mbps, 10Gbps	1Gbps, 10Gbps	Not Available	Not Available	Not Available
System Interface Type	PCIe Gen 2.1	PCIe Gen 2.1	PCIe Gen 2.1	PCIe Gen 2.1	PCIe 3.0	Not Available	PCIe M.2	PCIe M.2



						le		
NC Sideband Interface	Not Available	Not Available	Not Available	Not Available	Yes	Not Available	Not Available	Not Available
Jumbo Frames Supported	Yes	Yes	Yes	Yes	Yes	Not Available	Not Available	Not Available
1000Base-T	Yes	Yes	Yes	Yes	Not Available	Not Available	Not Available	Not Available
IEEE 1588	Supported	Supported	Supported	Not Available	Supported	Not Available	Not Available	Not Available
Supported Under vPro	Not Available	Not Available	Not Available	Not Available	Not Available	Not Available	Supported	Supported
Disclaimers								

## Ethernet Specifications Continued

Model	i210-T1	Dual Port Copper= I350-T2V2 Dual Port LC-Fiber= I350-F2	Dual Port Copper= I350-T4V2 Dual Port LC-Fiber= I350-F4	Dual Port Copper= X540-T2	X710-DA2	AC 7260 NGW	AC 8265 NGW
Connector	RJ-45 Copper	2 x Ports RJ-45 Copper or 2 x Ports LC-Fiber	4 x Ports RJ-45 Copper or 4 x Ports LC-Fiber	2 x Ports RJ-45 Copper	2 x SFPs Receptacle	2 x Antennas	2 x Antennas
Website	i210 T1	i350 T2/F2	i350 T4/F4	x540 T2	x710 DA2	7260 NGW	8265 NGW
Auto-Negotiation	IEEE* 802.3* Auto-negotiation	IEEE* 802.3* Auto-negotiation	IEEE* 802.3* Auto-negotiation	IEEE* 802.3* Auto-negotiation	IEEE* 802.3* Auto-negotiation	Not Available	Not Available
Intel® vPro™	Not Available	Not Available	Not Available	Not Available	Not Available	Supported	Supported
Intel® Standard Manageability	Supported	Supported	Supported	Supported	Supported	Not Available	Not Available
Power Optimizer Platform Low-power Management Systems	Supported	Supported	Supported	Supported	Supported	Supported	Supported
Energy Efficient Ethernet	Supported	Supported	Supported	Not Available	Supported	Not Available	Not Available

TCP/UDP Checksum and Segmentation Offload (IPv4 and IPv6)	Supported	Supported	Supported	Supported	Supported	Not Available	Not Available
Receive Side Scaling	Supported	Supported	Supported	Supported	Supported	Not Available	Not Available
Dual Tx and Rx Queues	Yes	Yes	Yes	Yes	Yes	Not Available	Not Available
Jumbo Frames (up to 9KB)	Supported	Supported	Supported	Not Available	Supported	Not Available	Not Available
Teaming	Supported	Supported	Supported	Supported	Supported	Not Available	Not Available
Wake from Deep Sx	Supported	Supported	Supported	Not Available	Not Available	Not Available	Not Available
Server Operating System Support	Windows Server 2008, 2012, 2016, 2019 Linux (RHEL/SLES), Free BSD, Xen, Vmware	Windows Server 2008, 2012, 2016, 2019 Linux (RHEL/SLES), Free BSD, Xen, Vmware	Windows Server 2008, 2012, 2016, 2019 Linux (RHEL/SLES), Free BSD, Xen, Vmware	Windows Server 2003, 2008; RHEL 4, Linux/SL ES 11, Vmware	Windows 2008, 2012; RHEL 6.5/7.0, FreeBSD 9/10, Vmware ESXi 5.x	Not Available	Not Available
Network Proxy/ARP Support	Supported	Supported	Supported	Supported	Supported	Not Available	Not Available
Disclaimers							

## Media Card Reader

---

Description	9-in-1 (USB 2.0)
Disclaimers	

## BIOS Specifications

---

WMI Support	Compliant With Microsoft WBEM and the DMTF Common Information Model
ROM-Based Setup Utility (F1)	System Configuration Setup Program (text only interface) Available at Power-on With F1 Key
Bootblock Recovery	Recovers System BIOS if the Flash ROM Becomes Corrupted

Replicated Setup	Saves System Configuration Settings to a File That Can Then be Used to Replicate the Settings to Other Systems
Boot Control	Boot Control Available Through ROM-based Setup Utility or With F12 Key at Power-on
Memory Change Alert	Power-on Error Message in the Event of a Decrease in System Memory
Thermal Alert	Power-on Error message in the Event of a Fan Failure
Asset Tag	Supports Ability to Set SMBIOS Type 2 Baseboard Asset Tag Field
System/Emergency ROM Flash Recovery With Video	Supports Process to Recover the System BIOS if the Flash ROM Becomes Corrupted
Remote Wakeup/Remote Shutdown	System Admin Can Power On/Off a Client Computer from a Remote Location to Provide Maintenance
Quick Resume Time	Supports Low Power S3 (suspend to RAM) and Prompt Resume Times
ROM Revision Level	System UEFI (BIOS) Version Reported in SMBIOS Type 0 Structure and in BIOS Setup
Keyboard-less Operation	System Can be Booted Without a Keyboard
Per-port Control	Allows I/O Ports to be Individually Enabled/Disabled Through ROM-based Setup or WMI Interface
Adaptive Cooling	Offers Multiple Settings for Fan Control Ranging Between Better Performance and Better Acoustics
Security	User and Administrator Passwords Can Protect Boot and ROM-based Setup <ul style="list-style-type: none"> <li>- Support Electronic Lock</li> <li>- Chassis Intrusion Detection</li> <li>- UEFI Secure Boot Support</li> <li>- HDD Password Can Protect HDD Data</li> <li>- Windows UEFI Firmware Update Support</li> <li>- Device Guard Support</li> <li>- Optional Access Panel Lock, Kensington Lock, and Pad Lock</li> </ul>
Intel(R) AMT (includes ASF 2.0)	Allows System to be Supported from a Remote Location
Intel(R) TXT	Intel(R) Trusted Execution Technology Provides a Security Foundation to Build Protections Against Software Based Attacks
Memory Modes	Supports Mirroring, Lock Step, and Sparing Memory Modes
Windows 10 Ready	Supports Windows 10 Requirements for Secure Flash, UEFI v 2.6 Device Guard Support Spec

## Industry Standard Specification Support

---

UEFI	Unified Extensible Firmware Interface v2.7
ACPI (Advanced Configuration and Power management Interface)	Advanced Configuration and Power Interface v6.1
ASF 2.0	DMTF Alert Standard Format Specification v2.0
ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6)
CD Boot	EI Torito Bootable CD-Rom Format Specification, v1.0
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision v1.0

PCI	NA (No PCI slot)
PCI Express	PCI Express Base Specification v3.0
SATA	Serial ATA Revision 3.0 Specification
TPM	Trusted Computing Group TPM Specification v2.0
UHCI	Universal Host Controller Interface Design Guide, Revision v1.1
USB	Universal Serial Bus Revision v1.1 Universal Serial Bus v2.0 Universal Serial Bus v3.0
SMBIOS	DMTF System Management Spec v3.2.1
XHCI	XHCI SPEC Revision v1.2

## Social And Environmental Responsibility

---

Quality Control	Lenovo is a member of an eco declaration system that enforces regular independent quality control
Hazardous Substances and Preparation	<ul style="list-style-type: none"> <li>· Products do not contain more than; 0.1% lead, 0.01% cadmium, 0.1% mercury, 0.1% hexavalent chromium, 0.1% polybrominated biphenyls (PBB) or 0.1% polybrominated diphenyl ethers (PBDE). (See legal reference and Note B1)</li> <li>· Products do not contain Asbestos</li> <li>· Products do not contain Ozone Depleting Substances: Chlorofluorocarbons (CFC), hydrobromofluorocarbons (HBFC), hydrochlorofluorocarbons (HCFC), Halons, carbontetrachloride, 1,1,1-trichloroethane, methyl bromide</li> <li>· Products do not contain more than; 0.005% polychlorinated biphenyl (PCB), 0.005% polychlorinated terphenyl (PCT) in preparation</li> <li>· Products do not contain more than 0.1% short chain chloroparaffins (SCCP) with 10-13 carbon atoms in the chain containing at least 48% per mass of chlorine in the SCCP</li> <li>· Parts with direct and prolonged skin contact do not release nickel in concentrations above 0.5 microgram/cm<sup>2</sup>/week</li> </ul> REACH Article 33 information about substances in articles is available at: <a href="http://www.lenovo.com/social_responsibility/us/en/ThinkGreen_products.html#environment">http://www.lenovo.com/social_responsibility/us/en/ThinkGreen_products.html#environment</a>
Batteries	Not Available
Safety, EMC Connection to the Telephone Network and Labeling	Not Applicable, no Connection to a Telephone Network

## Safety, EMC Connection To The Telephone Network And Labeling

---

System Software Manager	Lenovo ThinkStation Supports Software Management Tools by Lenovo Vantage
-------------------------	--

## Regulations & Standards

---

EMC & Safety	<p>FCC DoC for North America  VCCI Certification for Japan  BSMI Certification for Taiwan  EU/EFTA CE Mark &amp; DoC  UL/CUL(P920,P720,P520,P520c), cTUVus(P330)  UL-GS(P920,P720,P520,P520c), TUV-GS(P330)  IEC60950-1 CB Report/Certificate  Saudi Arabia SASO  Kuwait KUCAS  China CCC Mark  Hong Kong SAR (CB report)  Singapore PSB  South Africa SABS  Russia-EAC  Morocco-CM  Mexico-NOM  Kazakhstan-EAC  Belarus-EAC  Serbia KVALITET  Ukraine UKrCEPRO  India-BIS  USA Chemical Emission Test</p>
--------------	--

## Environmentals

---

Energy Star	ENERGY STAR® v7.0
EPEAT	EPEAT® Silver Certification Available on Select Models
Greenguard	Greenguard
RoHS	RoHS Compliant
ErP Lot-3 2013	Yes
Hazardous Substances	<ul style="list-style-type: none"> <li>· Products do not contain more than; 0.1% lead, 0.01% cadmium, 0.1% mercury, 0.1% hexavalent chromium, 0.1% polybrominated biphenyls (PBB) or 0.1% polybrominated diphenol ethers (PBDE)</li> <li>· Products do not contain Asbestos</li> <li>· Products do not contain Ozone Depleting Substances: Chlorofluorocarbons (CFC), hydrobromofluorocarbons (HBFC), hydrochlorofluorocarbons (HCFC), Halons, carbontetrachloride, 1,1,1-trichloroethane, methyl bromide</li> <li>· Products do not contain more than; 0.005% polychlorinated biphenyl (PCB), 0.005% polychlorinated terphenyl (PCT) in preparation</li> <li>· Products do not contain more than 0.1% short chain chloroparaffins (SCCP) with 10-13 carbon atoms in the chain containing at least 48% per mass of chlorine in the SCCP</li> <li>· Parts with direct and prolonged skin contact do not release nickel in concentrations above 0.5 microgram/cm<sub>2</sub>/week</li> </ul>
TCO Certification	9.0
Disclaimers	EPEAT registered where applicable. EPEAT registration varies by country. See <a href="http://www.epeat.net">www.epeat.net</a> for registration status by country.